

RD3H080SP

Pch -45V -8A Power MOSFET

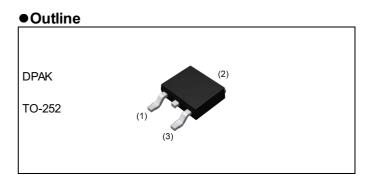
V _{DSS}	-45V
R _{DS(on)} (Max.)	91mΩ
I _D	±8A
P _D	15W

Features

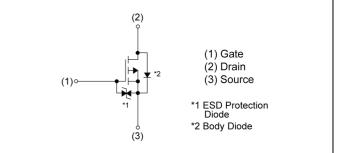
Application

Switching

- 1) Low on resistance
- 2) Fast switching speed
- 3) Drive circuits can be simple
- 4) Parallel use is easy
- 5) Pb-free lead plating ; RoHS compliant



Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
_	Tape width (mm)	16
Туре	Basic ordering unit (pcs)	2500
	Taning and a	TL
	Taping code	TL1
	Marking	RD3H080SP

●Absolute maximum ratings (T _a = 25°C ,unless otherwise specified)								
Parameter	Symbol	Value	Unit					
Drain - Source voltage	V _{DSS}	-45	V					
Continuous drain current	I _D *1	±8	А					
Pulsed drain current	ا _{DP} *2	±16	А					
Gate - Source voltage	V _{GSS}	±20	V					
Power dissipation	P _D *3	15	W					
Junction temperature	Tj	150	°C					
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C					

•Thermal resistance

Deremeter	Symbol	Values			
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}^{*3}	-	-	8.33	°C/W

• Electrical characteristics (T_a = 25°C)

Deremeter	Currente e l	Conditions	Values			Unit	
Parameter	Symbol Conditions –		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -1mA	-45	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	I _D = -1mA referenced to 25°C	-	-50	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	V _{DS} = -45V, V _{GS} = 0V	-	-	-1	μA	
Gate - Source leakage current	I _{GSS}	V_{GS} = ±20V, V_{DS} = 0V	-	-	±10	μA	
Gate threshold voltage	$V_{GS(th)}$	V _{DS} = -10V , I _D = -1mA	-1.0	-	-3.0	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = -1mA referenced to 25°C	-	3.3	-	mV/°C	
		V _{GS} = -10V, I _D = -8A	-	65	91		
Static drain - source on - state resistance	R _{DS(on)} *4	V _{GS} = -4.5V, I _D = -8A	-	95	133	mΩ	
		V _{GS} = -4.0V, I _D = -8A	-	105	147		
Gate resistance	R _G	f = 1MHz, open drain	-	8.8	-	Ω	
Forward Transfer Admittance	Y _{fs} ^{*4}	V _{DS} = -10V, I _D = -8A	6.0	-	-	S	

*1 Limited only by maximum temperature allowed.

*2 Pw \leq 10µs , Duty cycle \leq 1%

*3 T_C=25°C

*4 Pulsed



• Electrical characteristics ($T_a = 25^{\circ}C$)

Deremeter	Sumphal	Conditions		Values		Lincit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V	-	1000	-	
Output capacitance	C _{oss}	V _{DS} = -10V	-	160	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	80	-	
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq -25 V, V_{GS} = -10 V$	-	12	-	
Rise time	t _r *4	I _D = -4A	-	15	-	20
Turn - off delay time	$t_{d(off)}^{*4}$	$R_L \simeq 6.25\Omega$	-	50	-	ns
Fall time	t_{f}^{*4}	R _G = 10Ω	-	20	-	

• Gate charge characteristics ($T_a = 25^{\circ}C$)

Parameter	Symbol	Conditions		Values	-	Unit
	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Q _g *4	V _{DD} ≃ -25V,	-	9.0	-	
Gate - Source charge	Q _{gs} *4	I _D = -8A, V _{GS} = -5V	-	4.0	-	nC
Gate - Drain charge	${\sf Q}_{\sf gd}{}^{*4}$	V _{GS} = -5V	-	3.0	-	

•Body diode electrical characteristics (Source-Drain) ($T_a = 25^{\circ}C$)

Parameter	Symbol	Conditions		Values		Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	۱ _s *1	$T = 25^{\circ}$	-	-	-8	А
Pulse forward current	I _{SP} *2	T _a = 25°C	-	-	-16	А
Forward voltage	V_{SD}^{*4}	V _{GS} = 0V, I _S = -8A	-	-	-1.2	V



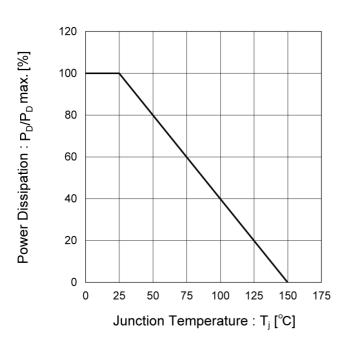


Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

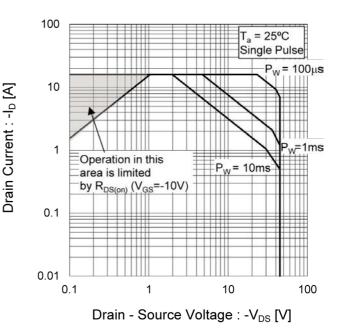
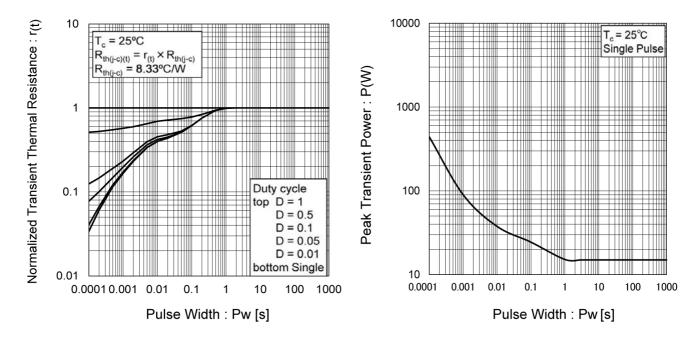


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

Fig.4 Single Pulse Maximum Power dissipation





V_{GS}=-2.6V

8

10

Electrical characteristic curves

V_{GS}=-10V

V_{GS}=-4.5V

V_{GS}=-4.0V

0.2

0

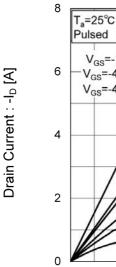


Fig.5 Typical Output Characteristics(I)

8 T_a=25°C V_{GS}=-10V Pulsed V_{GS}=-4.5V V_{GS}=-4.0V 6 V_{GS}=-3.6V V_{GS}=-3.0V 4 V_{GS}=-2.8V 2

4

6

Drain - Source Voltage : -V_{DS} [V]

Drain Current : -I_D [A]

0

0

2

V_{GS}=-3.6V

V_{GS}=-3.0V

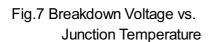
V_{GS}=-2.8V

V_{GS}=-2.6V

1.0

0.8

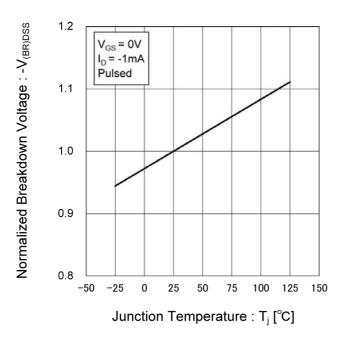
Fig.6 Typical Output Characteristics(II)



0.4

0.6

Drain - Source Voltage : -V_{DS} [V]





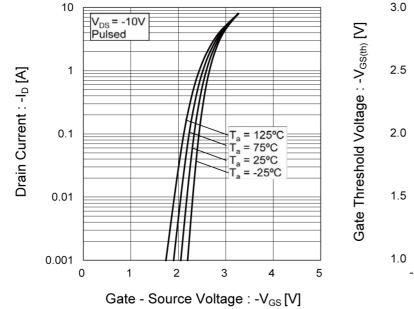


Fig.8 Typical Transfer Characteristics

Fig.9 Gate Threshold Voltage vs. Junction Temperature

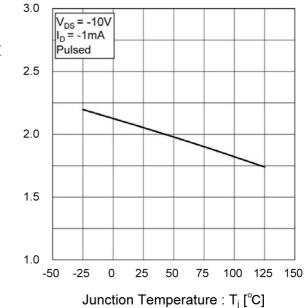
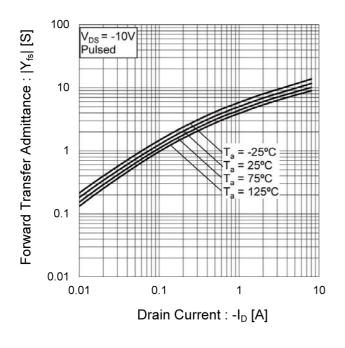


Fig.10 Forward Transfer Admittance vs. Drain Current





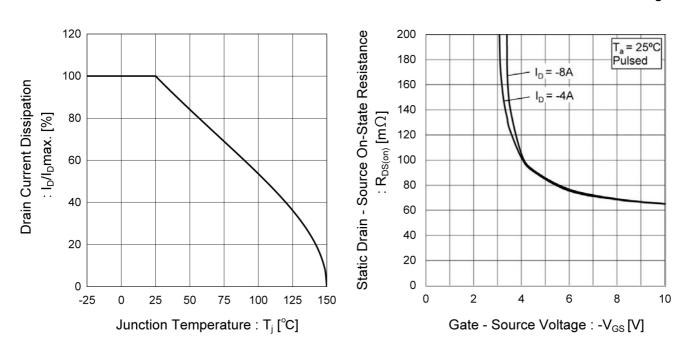
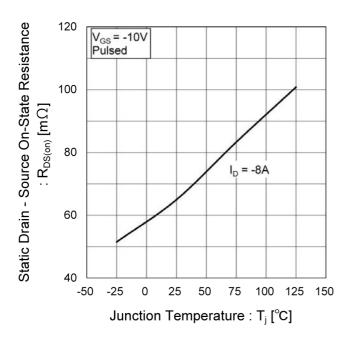


Fig.11 Drain Current Derating Curve

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature





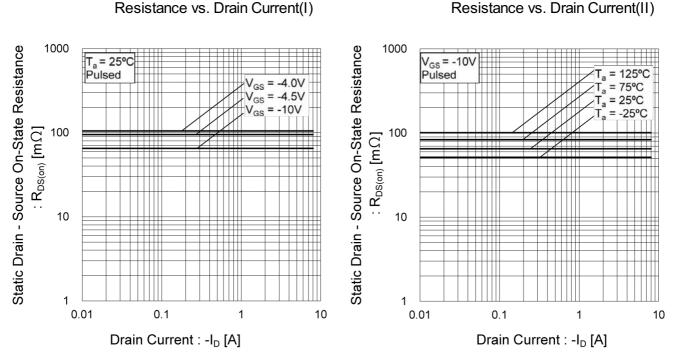


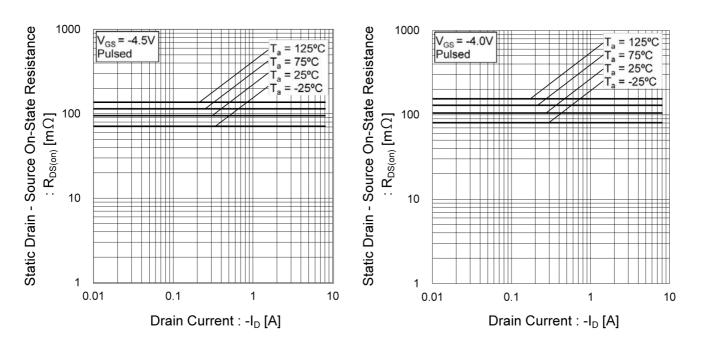
Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

Fig.16 Static Drain - Source On - State

Resistance vs. Drain Current(III)

Fig.17 Static Drain - Source On - State Resistance vs. Drain Current(IV)

Fig.15 Static Drain - Source On - State





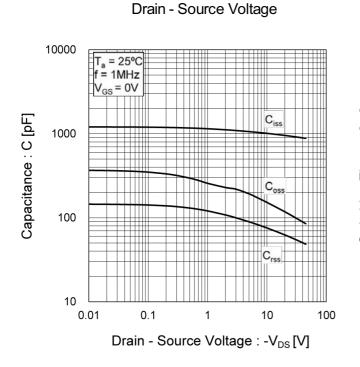


Fig.18 Typical Capacitance vs.

Fig.19 Switching Characteristics

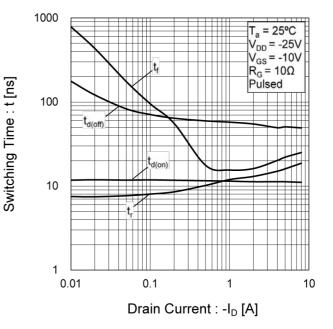


Fig.20 Dynamic Input Characteristics

Gate - Source Voltage : -V_{GS} [V]

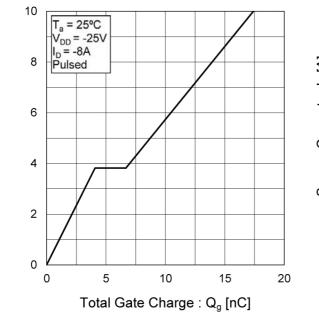
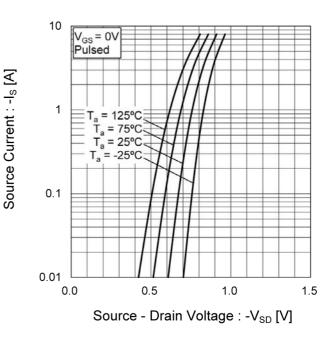


Fig.21 Source Current vs. Source Drain Voltage







Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

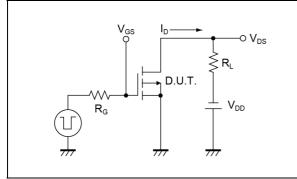


Fig.2-1 Gate Charge Measurement Circuit

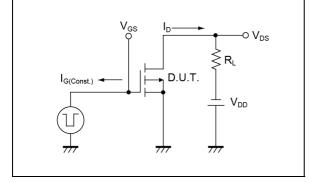
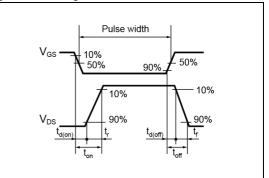
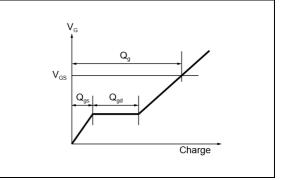


Fig.1-2 Switching Waveforms

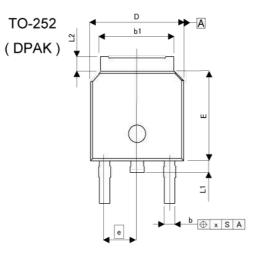


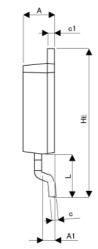


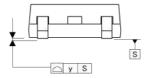


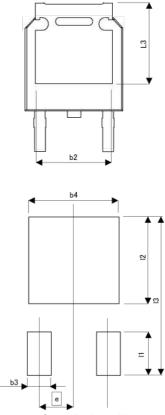


$\bullet \textit{Dimensions}(\mathsf{TL})$









Pattern of terminal position areas [Not a recommended pattern of soldering pads]

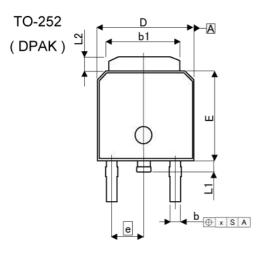
DIM -	MILIME	ETERS	INC	HES
	MIN	MAX	MIN	MAX
A	2.10	2.30	0.083	0.091
A1	0.70	1.10	0.028	0.043
b	0.65	0.85	0.026	0.033
b1	5.10	5.40	0.201	0.213
b2	5.	5.10		201
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.091	
E	6.00	6.40	0.236	0.252
HE	9.50	10.50	0.374	0.413
L	2.	90	0.114	
L1	0.70	0.90	0.028	0.035
L2	0.70	1.30	0.028	0.051
L3	5.30		0.2	209
x	-	0.10	14	0.004
у	-	0.10	-	0.004
	NALL IN A	TERS	INC	HES

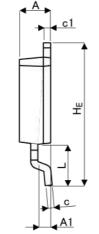
DIM -	MILIMETERS		INCHES	
DIVI	MIN	MAX	MIN	MAX
b3	<u>8</u>	1.10	61 <u>2</u> 2	0.043
b4	π.	5.40	2.52	0.213
11	¥ ()	2.90	17 <u>4</u> 1	0.114
12		5.50	5 .	0.217
13	<u>i</u>	10.50	023	0.413

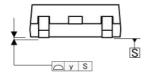
Dimension in mm/inches

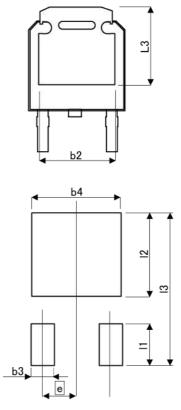


• Dimensions (TL1)









Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A	2.20	2.40	0.087	0.094
A1	0.70	1.10	0.028	0.043
b	0.60	0.90	0.024	0.035
b1	5.20	5.50	0.205	0.217
b2	4.	80	0.1	89
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
e	2.30		0.0)91
E	6.00	6.40	0.236	0.252
HE	9.40	10.40	0.370	0.409
L	2.	90	0.114	
L1	0.60	1.00	0.024	0.039
L2	0.70	1.30	0.028	0.051
L3	5.	30	0.209	
x	÷ (0.25		0.010
у	2	0.10	(7)	0.004
DIM -	MILIME	ETERS	INC	HES
	MIN	MAX	MIN	MAX
b3	×	1.15	(#)	0.045
b4		5.55	6751	0.219
11	÷ (2.77	100 (NR)	0.109
12		5.50	(2)	0.217
13	-	10.40	2篇0	0.409

Dimension in mm/inches



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I	CLASSⅢ	CLASSI	CLASS II b	CLASSⅢ
	CLASSⅣ		CLASSⅢ	

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 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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